

Product Change Notification - LIAL-03ASLT650

Date: 16 Jan 2018

Product Category: 16-Bit - Microcontrollers and Digital Signal Controllers; 8-bit PIC Microcontrollers; Ethernet Controllers

Notification subject: CCB 3221, 3221.001-3221.003 Initial Notice: Qualification of MMT as an additional assembly site for selected products of 0.25um TSMC wafer technology available in 64L, 28L QFN-S, 44L and 28L packages

Notification text: **PCN Status:**
Initial notification.

PCN Type:
Manufacturing Change

Microchip Parts Affected:
Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:
Qualification of MMT as an additional assembly site for selected products of 0.25um TSMC wafer technology available in 64L,28L QFN-S, 44L and 28L packages.

Pre Change:
Assembled at MTAI assembly site using gold (Au) wire.

Post Change:
Assembled at MTAI assembly site using gold (Au) wire and MMT assembly site using palladium coated copper wire with gold flash (CuPdAu).

Pre and Post Change Summary:

	Pre Change	Post Change	
Assembly Site	Microchip Technology Thailand HQ (MTAI)	Microchip Technology Thailand HQ (MTAI)	Microchip Technology Thailand Branch (MMT)
Wire material	Au	Au	CuPdAu
Die attach material	3280	3280	
Molding compound material	G700LTD	G700LTD	
Lead frame material	C194	C194	

Impacts to Data Sheet:
None

Change Impact:
None

Reason for Change:
To improve on-time delivery performance by qualifying MMT as an additional assembly site using palladium coated copper wire with gold flash (CuPdAu).

Change Implementation Status:
In Progress

Estimated Qualification Completion Date:

April 2018

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	January 2018				-->	April 2018			
Workweek	01	02	03	04		14	15	16	17
Initial PCN Issue Date			X						
Qual Report Availability							X		
Final PCN Issue Date							X		

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:

January 16, 2018: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

- [PCN_LIAL-03ASLT650_AFFECTED_CPN.pdf](#)
- [PCN_LIAL-03ASLT650_QUAL_PLAN.pdf](#)
- [PCN_LIAL-03ASLT650_AFFECTED_CPN.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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LIAL-03ASLT650 CCB 3321,3221.001- 3221.003 Initial Notice: Qualification of MMT as an additional assembly site for selected products of 0.25um TSMC wafer technology available in 64L, 28L QFN-S, 44L and 28L packages

Affected Catalog Part Numbers (CPN)

PCN_LIAL-03ASLT650
CATALOG_PART_NBR
DSPIC33FJ06GS102A-E/MM
DSPIC33FJ06GS102A-I/MM
DSPIC33FJ06GS102AT-E/MM
DSPIC33FJ06GS102AT-I/MM
DSPIC33FJ06GS102-E/MM
DSPIC33FJ06GS102-I/MM
DSPIC33FJ06GS102T-E/MM
DSPIC33FJ06GS102T-I/MM
DSPIC33FJ06GS202A-E/MM
DSPIC33FJ06GS202A-I/MM
DSPIC33FJ06GS202AT-E/MM
DSPIC33FJ06GS202AT-I/MM
DSPIC33FJ06GS202-E/MM
DSPIC33FJ06GS202-E/MMC04
DSPIC33FJ06GS202-I/MM
DSPIC33FJ06GS202T-E/MM
DSPIC33FJ06GS202T-E/MMC04
DSPIC33FJ06GS202T-E/MMC06
DSPIC33FJ06GS202T-I/MM
DSPIC33FJ09GS302-E/MM
DSPIC33FJ09GS302-I/MM
DSPIC33FJ09GS302T-E/MM
DSPIC33FJ09GS302T-I/MM
DSPIC33FJ128GP202-E/MM
DSPIC33FJ128GP202-I/MM
DSPIC33FJ128GP202T-E/MM
DSPIC33FJ128GP202T-I/MM
DSPIC33FJ128GP204-E/ML
DSPIC33FJ128GP204-I/ML
DSPIC33FJ128GP204T-E/ML
DSPIC33FJ128GP204T-I/ML
DSPIC33FJ128GP206A-E/MR
DSPIC33FJ128GP206A-I/MR
DSPIC33FJ128GP206AT-E/MR
DSPIC33FJ128GP206AT-I/MR
DSPIC33FJ128GP306A-E/MR
DSPIC33FJ128GP306A-I/MR
DSPIC33FJ128GP306AT-E/MR
DSPIC33FJ128GP306AT-I/MR
DSPIC33FJ128GP706A-E/MR
DSPIC33FJ128GP706A-H/MR
DSPIC33FJ128GP706A-I/MR
DSPIC33FJ128GP706AT-E/MR
DSPIC33FJ128GP706AT-H/MR
DSPIC33FJ128GP706AT-I/MR
DSPIC33FJ128GP802-E/MM
DSPIC33FJ128GP802-I/MM
DSPIC33FJ128GP802T-E/MM

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Affected Catalog Part Numbers (CPN)

PCN_LIAL-03ASLT650
CATALOG_PART_NBR
DSPIC33FJ128GP802T-I/MM
DSPIC33FJ128GP802T-I/MM038
DSPIC33FJ128GP802T-I/MM039
DSPIC33FJ128GP804-E/ML
DSPIC33FJ128GP804-H/ML
DSPIC33FJ128GP804-I/ML
DSPIC33FJ128GP804T-E/ML
DSPIC33FJ128GP804T-H/ML
DSPIC33FJ128GP804T-I/ML
DSPIC33FJ128MC202-E/MM
DSPIC33FJ128MC202-I/MM
DSPIC33FJ128MC202T-E/MM
DSPIC33FJ128MC202T-I/MM
DSPIC33FJ128MC204-E/ML
DSPIC33FJ128MC204-I/ML
DSPIC33FJ128MC204T-E/ML
DSPIC33FJ128MC204T-I/ML
DSPIC33FJ128MC506A-E/MR
DSPIC33FJ128MC506A-H/MR
DSPIC33FJ128MC506A-I/MR
DSPIC33FJ128MC506AT-E/MR
DSPIC33FJ128MC506AT-H/MR
DSPIC33FJ128MC506AT-I/MR
DSPIC33FJ128MC706A-E/MR
DSPIC33FJ128MC706A-H/MR
DSPIC33FJ128MC706A-I/MR
DSPIC33FJ128MC706AT-E/MR
DSPIC33FJ128MC706AT-H/MR
DSPIC33FJ128MC706AT-I/MR
DSPIC33FJ128MC802-E/MM
DSPIC33FJ128MC802-H/MM
DSPIC33FJ128MC802-I/MM
DSPIC33FJ128MC802T-E/MM
DSPIC33FJ128MC802T-H/MM
DSPIC33FJ128MC802T-I/MM
DSPIC33FJ128MC804-E/ML
DSPIC33FJ128MC804-H/ML
DSPIC33FJ128MC804-I/ML
DSPIC33FJ128MC804T-E/ML
DSPIC33FJ128MC804T-H/ML
DSPIC33FJ128MC804T-I/ML
DSPIC33FJ12GP202-E/ML
DSPIC33FJ12GP202-I/ML
DSPIC33FJ12GP202T-E/ML
DSPIC33FJ12GP202T-I/ML
DSPIC33FJ12MC202-E/ML
DSPIC33FJ12MC202-I/ML
DSPIC33FJ12MC202T-E/ML

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PCN_LIAL-03ASLT650
CATALOG_PART_NBR
DSPIC33FJ12MC202T-I/ML
DSPIC33FJ16GP102-E/ML
DSPIC33FJ16GP102-H/ML
DSPIC33FJ16GP102-I/ML
DSPIC33FJ16GP102T-E/ML
DSPIC33FJ16GP102T-I/ML
DSPIC33FJ16GP304-I/ML
DSPIC33FJ16GP304T-E/ML
DSPIC33FJ16GP304T-I/ML
DSPIC33FJ16GS402-50I/MM
DSPIC33FJ16GS402-E/MM
DSPIC33FJ16GS402-H/MM
DSPIC33FJ16GS402-I/MM
DSPIC33FJ16GS402T-50I/MM
DSPIC33FJ16GS402T-E/MM
DSPIC33FJ16GS402T-H/MM
DSPIC33FJ16GS402T-I/MM
DSPIC33FJ16GS404-50I/ML
DSPIC33FJ16GS404-E/ML
DSPIC33FJ16GS404-H/ML
DSPIC33FJ16GS404-I/ML
DSPIC33FJ16GS404T-50I/ML
DSPIC33FJ16GS404T-E/ML
DSPIC33FJ16GS404T-H/ML
DSPIC33FJ16GS404T-I/ML
DSPIC33FJ16GS502-50I/MM
DSPIC33FJ16GS502-E/MM
DSPIC33FJ16GS502-E/MMC03
DSPIC33FJ16GS502-H/MM
DSPIC33FJ16GS502-I/MM
DSPIC33FJ16GS502T-50I/MM
DSPIC33FJ16GS502T-E/MM
DSPIC33FJ16GS502T-E/MMC03
DSPIC33FJ16GS502T-H/MM
DSPIC33FJ16GS502T-I/MM
DSPIC33FJ16GS504-50I/ML
DSPIC33FJ16GS504-E/ML
DSPIC33FJ16GS504-H/ML
DSPIC33FJ16GS504-I/ML
DSPIC33FJ16GS504T-50I/ML
DSPIC33FJ16GS504T-E/ML
DSPIC33FJ16GS504T-H/ML
DSPIC33FJ16GS504T-I/ML
DSPIC33FJ16MC102-E/ML
DSPIC33FJ16MC102-H/ML
DSPIC33FJ16MC102-I/ML
DSPIC33FJ16MC102T-E/ML
DSPIC33FJ16MC102T-I/ML

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PCN_LIAL-03ASLT650
CATALOG_PART_NBR
DSPIC33FJ16MC304-E/ML
DSPIC33FJ16MC304-H/ML
DSPIC33FJ16MC304-I/ML
DSPIC33FJ16MC304T-E/ML
DSPIC33FJ16MC304T-I/ML
DSPIC33FJ256GP506A-E/MR
DSPIC33FJ256GP506A-I/MR
DSPIC33FJ256GP506AT-E/MR
DSPIC33FJ256GP506AT-I/MR
DSPIC33FJ32GP102-I/ML
DSPIC33FJ32GP104-I/ML
DSPIC33FJ32GP202-E/MM
DSPIC33FJ32GP202-I/MM
DSPIC33FJ32GP202T-E/MM
DSPIC33FJ32GP202T-I/MM
DSPIC33FJ32GP204-I/ML
DSPIC33FJ32GP204T-E/ML
DSPIC33FJ32GP204T-I/ML
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DSPIC33FJ32GP302-I/MM
DSPIC33FJ32GP302T-E/MM
DSPIC33FJ32GP302T-E/MMC03
DSPIC33FJ32GP302T-I/MM
DSPIC33FJ32GP304-E/ML
DSPIC33FJ32GP304-I/ML
DSPIC33FJ32GP304T-E/ML
DSPIC33FJ32GP304T-I/ML
DSPIC33FJ32GS406-50I/MR
DSPIC33FJ32GS406-I/MR
DSPIC33FJ32GS406T-50I/MR
DSPIC33FJ32GS606-50I/MR
DSPIC33FJ32GS606-E/MR
DSPIC33FJ32GS606-I/MR
DSPIC33FJ32GS606T-50I/MR
DSPIC33FJ32GS606T-I/MRC01
DSPIC33FJ32MC102-I/ML
DSPIC33FJ32MC104-I/ML
DSPIC33FJ32MC202-E/MM
DSPIC33FJ32MC202-H/MM
DSPIC33FJ32MC202-I/MM
DSPIC33FJ32MC202T-E/MM
DSPIC33FJ32MC202T-H/MM
DSPIC33FJ32MC202T-I/MM
DSPIC33FJ32MC204-E/ML
DSPIC33FJ32MC204-H/ML
DSPIC33FJ32MC204-I/ML
DSPIC33FJ32MC204T-E/ML
DSPIC33FJ32MC204T-I/ML

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PCN_LIAL-03ASLT650
CATALOG_PART_NBR
DSPIC33FJ32MC204T-V/MLC21
DSPIC33FJ32MC204-V/MLC21
DSPIC33FJ32MC302-E/MM
DSPIC33FJ32MC302-I/MM
DSPIC33FJ32MC302T-E/MM
DSPIC33FJ32MC302T-I/MM
DSPIC33FJ32MC304-E/ML
DSPIC33FJ32MC304-I/ML
DSPIC33FJ32MC304T-E/ML
DSPIC33FJ32MC304T-I/ML
DSPIC33FJ64GP202-E/MM
DSPIC33FJ64GP202-I/MM
DSPIC33FJ64GP202T-E/MM
DSPIC33FJ64GP202T-I/MM
DSPIC33FJ64GP204-E/ML
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DSPIC33FJ64GP204T-E/ML
DSPIC33FJ64GP204T-I/ML
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DSPIC33FJ64GP206AT-I/MR
DSPIC33FJ64GP306A-E/MR
DSPIC33FJ64GP306A-I/MR
DSPIC33FJ64GP306AT-E/MR
DSPIC33FJ64GP306AT-I/MR
DSPIC33FJ64GP706A-E/MR
DSPIC33FJ64GP706A-I/MR
DSPIC33FJ64GP706AT-E/MR
DSPIC33FJ64GP706AT-I/MR
DSPIC33FJ64GP802-E/MM
DSPIC33FJ64GP802-H/MM
DSPIC33FJ64GP802-I/MM
DSPIC33FJ64GP802-I/MMB21
DSPIC33FJ64GP802T-E/MM
DSPIC33FJ64GP802T-E/MM032
DSPIC33FJ64GP802T-E/MM041
DSPIC33FJ64GP802T-H/MM
DSPIC33FJ64GP802T-I/MM
DSPIC33FJ64GP802T-I/MMB21
DSPIC33FJ64GP804-E/ML
DSPIC33FJ64GP804-I/ML
DSPIC33FJ64GP804T-E/ML
DSPIC33FJ64GP804T-I/ML
DSPIC33FJ64GS406-50I/MR
DSPIC33FJ64GS406-E/MR
DSPIC33FJ64GS406-I/MR
DSPIC33FJ64GS406T-50I/MR

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PCN_LIAL-03ASLT650
CATALOG_PART_NBR
DSPIC33FJ64GS606-50I/MR
DSPIC33FJ64GS606-E/MR
DSPIC33FJ64GS606-I/MR
DSPIC33FJ64GS606T-50I/MR
DSPIC33FJ64MC202-E/MM
DSPIC33FJ64MC202-E/MMC04
DSPIC33FJ64MC202-I/MM
DSPIC33FJ64MC202-I/MM030
DSPIC33FJ64MC202-I/MMC21
DSPIC33FJ64MC202T-E/MM
DSPIC33FJ64MC202T-E/MMC04
DSPIC33FJ64MC202T-I/MM
DSPIC33FJ64MC202T-I/MM030
DSPIC33FJ64MC202T-I/MMC21
DSPIC33FJ64MC204-E/ML
DSPIC33FJ64MC204-E/ML042
DSPIC33FJ64MC204-I/ML
DSPIC33FJ64MC204T-E/ML
DSPIC33FJ64MC204T-E/ML042
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DSPIC33FJ64MC506A-H/MR
DSPIC33FJ64MC506A-I/MR
DSPIC33FJ64MC506AT-E/MR
DSPIC33FJ64MC506AT-H/MR
DSPIC33FJ64MC506AT-I/MR
DSPIC33FJ64MC706A-E/MR
DSPIC33FJ64MC706A-I/MR
DSPIC33FJ64MC706AT-E/MR
DSPIC33FJ64MC706AT-I/MR
DSPIC33FJ64MC802-E/MM
DSPIC33FJ64MC802-H/MM
DSPIC33FJ64MC802-I/MM
DSPIC33FJ64MC802T-E/MM
DSPIC33FJ64MC802T-H/MM
DSPIC33FJ64MC802T-I/MM
DSPIC33FJ64MC804-E/ML
DSPIC33FJ64MC804-H/ML
DSPIC33FJ64MC804-I/ML
DSPIC33FJ64MC804T-E/ML
DSPIC33FJ64MC804T-H/ML
DSPIC33FJ64MC804T-I/ML
ENC28J60/MLC01
ENC28J60-I/ML
ENC28J60T-I/ML
HA7612-I/MM033
HA7612-I/MM036
HA7612T-I/MM033

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PCN_LIAL-03ASLT650
CATALOG_PART_NBR
HA7612T-I/MM036
HA7617-I/ML035
HA7617-I/ML040
HA7617T-I/ML035
HA7617T-I/ML040
HA7617T-I/ML044
HA7617T-I/ML046
PIC18F24J10-I/ML
PIC18F24J10T-I/ML
PIC18F24J11-I/ML
PIC18F24J11T-I/ML
PIC18F24J50-I/ML
PIC18F24J50T-I/ML
PIC18F25J10-I/ML
PIC18F25J10-I/ML020
PIC18F25J10T-I/ML
PIC18F25J10T-I/ML020
PIC18F25J11-I/ML
PIC18F25J11T-I/ML
PIC18F25J50-I/ML
PIC18F25J50T-I/ML
PIC18F26J11-I/ML
PIC18F26J11T-I/ML
PIC18F26J13-I/ML
PIC18F26J13T-I/ML
PIC18F26J50-I/ML
PIC18F26J50T-I/ML
PIC18F26J53-I/ML
PIC18F26J53T-I/ML
PIC18F27J13-I/ML
PIC18F27J13T-I/ML
PIC18F27J53-I/ML
PIC18F27J53T-I/ML
PIC18F44J10-I/ML
PIC18F44J11-I/ML
PIC18F44J11T-I/ML
PIC18F44J50-I/ML
PIC18F44J50T-I/ML
PIC18F45J10-I/ML
PIC18F45J10T-I/ML
PIC18F45J11-I/ML
PIC18F45J11T-I/ML
PIC18F45J50-I/ML
PIC18F45J50T-I/ML
PIC18F46J11-I/ML
PIC18F46J11T-I/ML
PIC18F46J13-I/ML
PIC18F46J13T-I/ML

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Affected Catalog Part Numbers (CPN)

PCN_LIAL-03ASLT650
CATALOG_PART_NBR
PIC18F46J50-I/ML
PIC18F46J50T-I/ML
PIC18F46J53-I/ML
PIC18F46J53T-I/ML
PIC18F47J13-I/ML
PIC18F47J13T-I/ML
PIC18F47J53-I/ML
PIC18F47J53T-I/ML
PIC18LF24J10-I/ML
PIC18LF24J11-I/ML
PIC18LF24J11T-I/ML
PIC18LF24J50-I/ML
PIC18LF24J50T-I/ML
PIC18LF25J10-I/ML
PIC18LF25J10T-I/ML
PIC18LF25J11-I/ML
PIC18LF25J11T-I/ML
PIC18LF25J50-I/ML
PIC18LF25J50T-I/ML
PIC18LF26J11-I/ML
PIC18LF26J11T-I/ML
PIC18LF26J13-I/ML
PIC18LF26J13T-I/ML
PIC18LF26J50-I/ML
PIC18LF26J50T-I/ML
PIC18LF26J53-I/ML
PIC18LF26J53T-I/ML
PIC18LF27J13-I/ML
PIC18LF27J13T-I/ML
PIC18LF27J53-I/ML
PIC18LF27J53T-I/ML
PIC18LF44J10-I/ML
PIC18LF44J11-I/ML
PIC18LF44J11T-I/ML
PIC18LF44J50-I/ML
PIC18LF44J50T-I/ML
PIC18LF45J10-I/ML
PIC18LF45J11-I/ML
PIC18LF45J11T-I/ML
PIC18LF45J50-I/ML
PIC18LF45J50T-I/ML
PIC18LF46J11-I/ML
PIC18LF46J11T-I/ML
PIC18LF46J13-I/ML
PIC18LF46J13T-I/ML
PIC18LF46J50-I/ML
PIC18LF46J50T-I/ML
PIC18LF46J53-I/ML

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Affected Catalog Part Numbers (CPN)

PCN_LIAL-03ASLT650
CATALOG_PART_NBR
PIC18LF46J53T-I/ML
PIC18LF47J13-I/ML
PIC18LF47J13T-I/ML
PIC18LF47J53-I/ML
PIC18LF47J53T-I/ML
PIC24FJ128GA006-I/MR
PIC24FJ128GA106-E/MR
PIC24FJ128GA106-I/MR
PIC24FJ128GA106T-I/MR
PIC24FJ128GB106-I/MR
PIC24FJ128GB106T-I/MR
PIC24FJ16GA002-E/ML
PIC24FJ16GA002-I/ML
PIC24FJ16GA002-I/MLB4
PIC24FJ16GA002-I/MLC10
PIC24FJ16GA002T-E/ML
PIC24FJ16GA002T-I/ML
PIC24FJ16GA002T-I/ML023
PIC24FJ16GA002T-I/MLC05
PIC24FJ16GA002T-I/MLC06
PIC24FJ16GA004-E/ML
PIC24FJ16GA004-I/ML
PIC24FJ16GA004T-I/ML
PIC24FJ16GA004T-I/MLC09
PIC24FJ16MC102-E/ML
PIC24FJ16MC102-H/ML
PIC24FJ16MC102-I/ML
PIC24FJ16MC102T-E/ML
PIC24FJ16MC102T-I/ML
PIC24FJ192GA106-E/MR
PIC24FJ192GA106-I/MR
PIC24FJ192GB106-I/MR
PIC24FJ256GA106-E/MR
PIC24FJ256GA106-I/MR
PIC24FJ256GA106T-E/MR
PIC24FJ256GA106T-I/MR
PIC24FJ256GB106-I/MR
PIC24FJ256GB106T-I/MR
PIC24FJ32GA002-E/ML
PIC24FJ32GA002-I/ML
PIC24FJ32GA002T-E/ML
PIC24FJ32GA002T-I/ML
PIC24FJ32GA002T-I/ML030
PIC24FJ32GA002T-I/ML031
PIC24FJ32GA002T-I/MLC06
PIC24FJ32GA002T-I/MLC11
PIC24FJ32GA004-E/ML
PIC24FJ32GA004-I/ML

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Affected Catalog Part Numbers (CPN)

PCN_LIAL-03ASLT650
CATALOG_PART_NBR
PIC24FJ32GA004T-E/ML
PIC24FJ32GA004T-I/ML
PIC24FJ32GA004T-I/MLC12
PIC24FJ32GA102-E/ML
PIC24FJ32GA102-I/ML
PIC24FJ32GA102T-I/ML
PIC24FJ32GA104-E/ML
PIC24FJ32GA104-I/ML
PIC24FJ32GA104-I/ML021
PIC24FJ32GA104-I/ML023
PIC24FJ32GA104-I/ML025
PIC24FJ32GA104T-E/ML
PIC24FJ32GA104T-I/ML
PIC24FJ32GA104T-I/ML021
PIC24FJ32GA104T-I/ML023
PIC24FJ32GA104T-I/ML024
PIC24FJ32GA104T-I/ML025
PIC24FJ32GB002-I/ML
PIC24FJ32GB002T-I/ML
PIC24FJ32GB002T-I/MLC01
PIC24FJ32GB004-I/ML
PIC24FJ32GB004T-I/ML
PIC24FJ32MC102-E/ML
PIC24FJ32MC102-I/ML
PIC24FJ32MC102T-I/ML
PIC24FJ32MC104-I/ML
PIC24FJ48GA002-I/ML
PIC24FJ48GA002-I/MLB
PIC24FJ48GA002T-I/ML
PIC24FJ48GA002T-I/MLB
PIC24FJ48GA004-E/ML
PIC24FJ48GA004-I/ML
PIC24FJ48GA004T-I/ML
PIC24FJ48GA004T-I/ML022
PIC24FJ64GA002-E/ML
PIC24FJ64GA002-I/ML
PIC24FJ64GA002-I/ML022
PIC24FJ64GA002T-E/ML
PIC24FJ64GA002T-I/ML
PIC24FJ64GA002T-I/ML022
PIC24FJ64GA002T-I/MLC03
PIC24FJ64GA004-E/ML
PIC24FJ64GA004-I/ML
PIC24FJ64GA004-I/MLB4
PIC24FJ64GA004T-I/ML
PIC24FJ64GA004T-I/MLC13
PIC24FJ64GA006-I/MR
PIC24FJ64GA006T-I/MR

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Affected Catalog Part Numbers (CPN)

PCN_LIAL-03ASLT650
CATALOG_PART_NBR
PIC24FJ64GA102-I/ML
PIC24FJ64GA102T-I/ML
PIC24FJ64GA104-E/ML
PIC24FJ64GA104-I/ML
PIC24FJ64GA104T-E/ML
PIC24FJ64GA104T-I/ML
PIC24FJ64GA106-E/MR
PIC24FJ64GA106-I/MR
PIC24FJ64GA106T-I/MR
PIC24FJ64GA106T-I/MR029
PIC24FJ64GA106T-I/MR032
PIC24FJ64GA106T-I/MR033
PIC24FJ64GA106T-I/MR035
PIC24FJ64GB002-I/ML
PIC24FJ64GB002T-I/ML
PIC24FJ64GB004-I/ML
PIC24FJ64GB004T-I/ML
PIC24FJ64GB106-I/MR
PIC24FJ96GA006-I/MR
PIC24HJ128GP202-E/MM
PIC24HJ128GP202-I/MM
PIC24HJ128GP202T-E/MM
PIC24HJ128GP202T-I/MM
PIC24HJ128GP204-E/ML
PIC24HJ128GP204-I/ML
PIC24HJ128GP204T-E/ML
PIC24HJ128GP204T-I/ML
PIC24HJ128GP206A-E/MR
PIC24HJ128GP206A-I/MR
PIC24HJ128GP206AT-E/MR
PIC24HJ128GP206AT-I/MR
PIC24HJ128GP306A-E/MR
PIC24HJ128GP306A-I/MR
PIC24HJ128GP306AT-E/MR
PIC24HJ128GP306AT-I/MR
PIC24HJ128GP502-E/MM
PIC24HJ128GP502-H/MM
PIC24HJ128GP502-I/MM
PIC24HJ128GP502T-E/MM
PIC24HJ128GP502T-H/MM
PIC24HJ128GP502T-I/MM
PIC24HJ128GP504-E/ML
PIC24HJ128GP504-H/ML
PIC24HJ128GP504-I/ML
PIC24HJ128GP504T-E/ML
PIC24HJ128GP504T-H/ML
PIC24HJ128GP504T-I/ML
PIC24HJ128GP506A-E/MR

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Affected Catalog Part Numbers (CPN)

PCN_LIAL-03ASLT650
CATALOG_PART_NBR
PIC24HJ128GP506A-H/MR
PIC24HJ128GP506A-I/MR
PIC24HJ128GP506AT-E/MR
PIC24HJ128GP506AT-H/MR
PIC24HJ128GP506AT-I/MR
PIC24HJ12GP202-E/ML
PIC24HJ12GP202-I/ML
PIC24HJ16GP304-H/ML
PIC24HJ16GP304-I/ML
PIC24HJ16GP304T-E/ML
PIC24HJ16GP304T-I/ML
PIC24HJ256GP206A-E/MR
PIC24HJ256GP206A-I/MR
PIC24HJ256GP206AT-E/MR
PIC24HJ256GP206AT-I/MR
PIC24HJ32GP202-E/MM
PIC24HJ32GP202-H/MM
PIC24HJ32GP202-I/MM
PIC24HJ32GP202T-I/MM
PIC24HJ32GP204-E/ML
PIC24HJ32GP204-I/ML
PIC24HJ32GP204T-E/ML
PIC24HJ32GP204T-I/ML
PIC24HJ32GP302-E/MM
PIC24HJ32GP302-I/MM
PIC24HJ32GP302T-E/MM
PIC24HJ32GP302T-I/MM
PIC24HJ32GP304-E/ML
PIC24HJ32GP304-I/ML
PIC24HJ32GP304T-E/ML
PIC24HJ32GP304T-I/ML
PIC24HJ64GP202-E/MM
PIC24HJ64GP202-I/MM
PIC24HJ64GP202T-E/MM
PIC24HJ64GP202T-I/MM
PIC24HJ64GP204-E/ML
PIC24HJ64GP204-I/ML
PIC24HJ64GP204T-E/ML
PIC24HJ64GP204T-I/ML
PIC24HJ64GP206A-E/MR
PIC24HJ64GP206A-I/MR
PIC24HJ64GP206A-I/MR031
PIC24HJ64GP206A-I/MRA28
PIC24HJ64GP206AT-E/MR
PIC24HJ64GP206AT-I/MR
PIC24HJ64GP206AT-I/MR031
PIC24HJ64GP206AT-I/MRA28
PIC24HJ64GP502-E/MM

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Affected Catalog Part Numbers (CPN)

PCN_LIAL-03ASLT650
CATALOG_PART_NBR
PIC24HJ64GP502-H/MM
PIC24HJ64GP502-I/MM
PIC24HJ64GP502T-E/MM
PIC24HJ64GP502T-H/MM
PIC24HJ64GP502T-I/MM
PIC24HJ64GP504-E/ML
PIC24HJ64GP504-I/ML
PIC24HJ64GP504T-E/ML
PIC24HJ64GP504T-I/ML
PIC24HJ64GP506A-E/MR
PIC24HJ64GP506A-I/MR
PIC24HJ64GP506AT-E/MR
PIC24HJ64GP506AT-I/MR